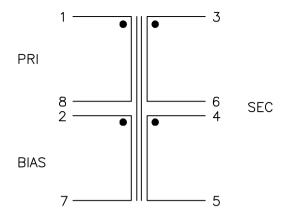


SUGGESTED PAD LAYOUT



## ELECTRICAL CHARACTERISTICS:

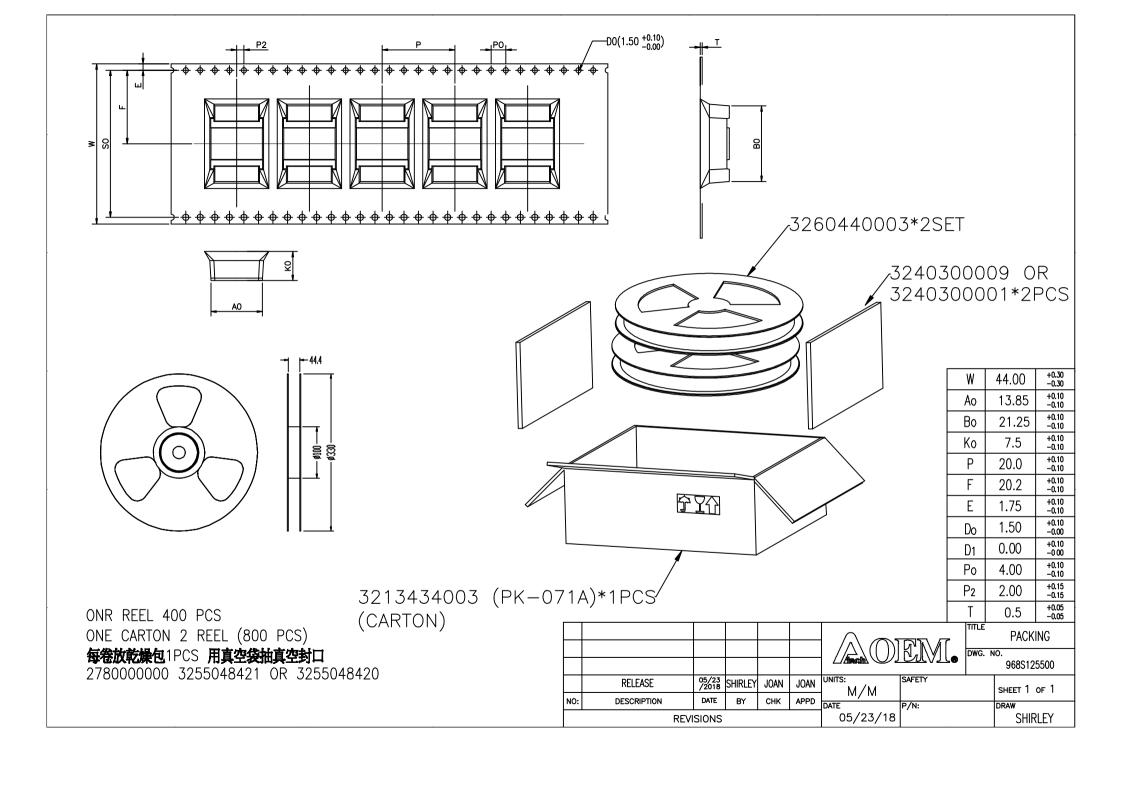
- 1. INDUCTANCE (@200KHz, 0.1Vrms) PIN 1-8 = 64uH  $\pm 10$ %
- 2. TURN RATIO (@250KHz, 0.1Vrms)

PIN 1-8 :  $2-7 = 0.852 \pm 3\%$ PIN 1-8 :  $3-6 = 2.556 \pm 3\%$ PIN 1-8 :  $4-5 = 2.556 \pm 3\%$ 

- 3. DCR : PIN  $1-8 = 190m\Omega$  MAX. PIN  $2-7 = 1.1\Omega$  MAX. PIN  $3-6 = 65m\Omega$  MAX. PIN  $4-5 = 70m\Omega$  MAX.
- 4. HI-POT (@1500VAC, 1mA, 1S) : PIN(1-3) ; PIN 6-4 SHORT
- 5. RoHS COMPLIANCE

								* TRANSFORMER
							R. Dwo	3. NO. ATS-1255R
	RELEASE	08/05 /2013	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY	SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	СНК	APPD	,	P/N:	DRAW
	REVI			08/05/13	,	Shirley		

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE ±0.25mm





## Pb-free Soldering IR Reflow(SMD)



1,MSL Grade: 1 Level 2,Floor life: 2years 3,Condition:≤30°C RH 85% 2,Form-1(Reference JEDEC J-STD-020D Table 5-2)

	IR reflow profile	Pb-free	
step#	Profile Feature	Condition/Duration	
step1	Ramp-up rate	3°C/second max	
step2	Preheat:150°C-200°C(Ta-Tb)	t1-t2:60-120seconds	
step3	Ramp-up rate(TL to Tp)	3°C/second max	
sieps	Temperature maintained above 217°C	60-150seconds	
ston/	Peak temperature(Tp)	260+0/-5℃	
step4	Time within 5°C of actual peak temperature	30seconds max	
	Ramp-down rate(Tp to TL)	6°C/second max	

## 3,Form-2(Reference JEDEC J-STD-020D Table 4-2)

Package	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>	Volume mm <sup>3</sup> >2000
Thickness	<350	350-2000	
<1.6mm	260+0/-5°C	260+0/-5°C	260+0/-5℃
1.6mm-2.5mm	260+0/-5°C	250+0/-5°C	245+0/-5℃
>2.5mm	250+0/-5° <b>C</b>	245+0/-5°C	245+0/-5℃